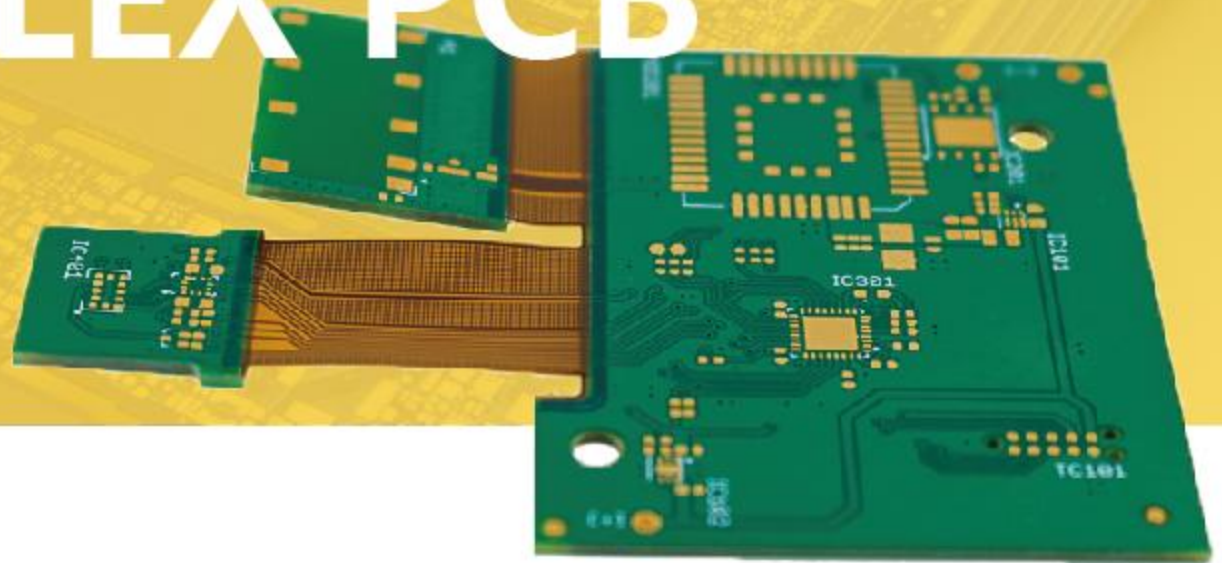


RIGID-FLEX PCB



CAPABILITIES

Layers	2 - 40L	Max Buried Via	8 mil
Max Board Size	15.75" x 23.5"	PTH Dia. Tolerance	±3 mil
Board Thickness	.00788" - .1968"	NPTH Dia. Tolerance	±2 mil
Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%	Hole Position Deviation	±3 mil
		Outline Tolerance	±4 mil
Min. Line Width	2.5 mil	Solder Mask Dams	3 mil
Min. Line Space	2.5 mil	Aspect Ratio Mechanical	20:1
Min. Mechanical Drill/Pad	6 mil 16 mil	Aspect Ratio Laser	1:1
Min. Laser Drill/Pad	4 mil 10 mil		

SURFACE FINISHES

- HASL/LF HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

MATERIALS

- FR4 low/mid/high TG
- Polyimide
- Polyimide Film
- (adhesive, adhesiveless):
Thicknesses - 1, 2, 3, 4, & 5 mil

CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

LEAD TIMES

Quick Turn, 10 - 15 Days from Asia
High Mix Low Volume
Medium to High Volume
* Technology level dependent



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Production Base

No.94 building, Sai'er Kong blvd,Xiangshan Community, ao'an district, Shenzhen.